



Z80 CPU Central Process Unit

- The instruction set contains 158 instructions. The 78 instructions of the 8080A are included as a subset; 8080A and 280° software compatibility is maintained.
- 8MHz, 6MHz, 4MHz and 2.5 MHz clocks for the Z80H, Z80B, Z80A and Z80 CPU result in rapid instruction execution with consequent high data throughput.
- The extensive instruction set includes string, bit, byte, and word operations. Block searches and block transfers together with indexed and relative addressing result in the most powerful data handling capabilities in the microcomputer industry.
- The 280 microprocessors and associated family of peripheral controllers are linked by a vectored interrupt system. This

system may be daisy-chained to allow implementation of a priority interrupt scheme. Little, if any, additional logic is required for daisy-chaining.

- Duplicate sets of both general-purpose and flag registers are provided, easing the design and operation of system software through single-context switching, background-foreground programming, and single-level interrupt processing. In addition, two I6-bit index registers facilitate program processing of tables and arrays.
- There are three modes of high speed interrupt processing: 8080 similar, non-280 peripheral device, and 280 Family peripheral with or without daisy chain.
- On-chip dynamic memory refresh counter.



Figure 1. Logic Functions



General Description

The Z80, Z80A, Z80B and Z80H CPUs are third-generation single-chip microprocessors with exceptional computational power. They offer higher system throughput and more efficient memory utilization than comparable second-and third-generation microprocessors. The internal registers contain 208 bits of read/write memory that are accessible to the programmer. These registers include two sets of six generalpurpose registers which may be used individually as either 8-bit registers or as 16-bit register pairs. In addition, there are two sets of accumulator and flag registers. A group of "Exchange" instructions makes either set of main or alternate registers accessible to the programmer. The alternate set allows operation in foregroundbackground mode or it may be reserved for very fast interrupt response.

The Z80 also contains a Stack Pointer, Program Counter, two index registers, a Refresh register (counter), and an Interrupt register.

The CPU is easy to incorporate into a system since it requires only a single +5 V power source. All output signals are fully decoded and timed to control standard memory or peripheral circuits, and it is supported by an extensive family of peripheral controllers. The internal block diagram (Figure 3) shows the primary functions of the Z80 processors. Subsequent text provides more detail on the Z80 L/O controller family, registers, instruction set, interrupts and daisy chaining, and CPU timing.

	-			
	1 2 3 4 5 8 8 10 11 12 13 14 15 16 17 18 19	28400	40 39 38 37 35 34 33 32 31 30 29 26 27 26 25 24 23 22	~ ~ ~ ~ ~ ~ ~ ~
MREO C	19		22	l wa
ORO C	20		21	
			-	

3 2 7 口^5 CLK [39 04 d ۵ ۹4 38 03 ٢ ΠA3 ٥, Г 10 36 06 Г h Ai 35 78400 N.C. [12 h٩٥ 34 v_{cc} [13 1 GND 33 02 D 14 RFSH 32 07 0:5 hm 31 ₽o [] 30 RESET 16 o, [BUSREO 29 20 27 23 24 25 26 27 28 5.8097 LILI 7 BUSACK WAIT N.C. NO CONNECTION

Figure 2. Pin Configuration

Figure 2a. Chip Carrier Pin Configuration



General Description (Continued)



Figure 3. CPU Block Diagram

280 Microprocessor Family

The Z80, Z80A, Z80B and Z80H microprocessor is the central element of a comprehensive microprocessor product family. This family works together in most applications with minimum requirements for additional logic, facilitating the design of efficent and cost-effective microcomputerbase systems.

Five components to provide extensive support for the Z80 microprocessor. These are:

- The CTC (Couter/Timer Circuit) features four programmable 8-bit counter/timers, each of which has an 8-bit prescaler. Each of the four channels may be configurated to operate in either counter or timer mode.
- The PIO (Parallel Input/Output) operates in both data-byte I/O transfer mode (with handshaking) and in bit mode (without handshaking). The PIO may be

configured to interface with standard parallel periperal devices such as printers, tape punches, and keyboards.

- The DMA (Direct Memory Access) controller provides dual port data transfer operations and the ability to teminate data transfer as a result of a pattern match.
- The SIO (Serial Input/Output) controller offers two channels. It is capable of operating in a variety of programmable medes for both synchronous and asynchronous communication, including Bi-Synch and SDLC.
- The DART (Dual Asynchronous Receiver/Transmitter) device provides low cost asynchronous serial communication. It has two channels and a full modem control interface.



Z80 CPU Registers

Figure 4 shows three groups of registers within the Z80 CPU. The first group consists of duplicate sets of 8-bit registers: a principal set and an alternate set (designated by ' [prime], e.g., A'). Both sets consist of the Accumulator Register, the Flag Register, and six general-purpose registers. Transfer of data between these duplicate sets of registers is accomplished by use of "Exchange" instructions. The result is faster response to interrupts and easy, efficient implementation of such versatile programming techniques as backgroundforeground data processing. The second set of registers consists of six registers with assigned functions. These are the I (Interrupt Register), the R (Refresh Register), the IX and IY (Index Registers), the SP (Stack Pointer), and the PC (Program Counter). The third group consists of two interrupt status flip-flops, plus and additional pair of flip-flops which assists in identifying the interrupt mode at any particular time. Table I provides further information on these registers.

MAIN REC	NSTER SET	ALTERNATE	REGISTER SET
A ACCUMULATOR	F FLAG REGISTER	A' ACCUMULATOR	F' FLAG REGISTER
B GENERAL PURPOSE	C GENERAL PURPOSE	B' GENERAL PURPOSE	C' OENERAL PURPOSE
D GENERAL PURPOSE	E GENERAL PURPOSE	D' GENERAL PURPOSE	E' DENERAL PURPOSE
H GENERAL PURPOSE	L GENERAL PURPOSE	H' GENERAL PURPOSE	L' GENERAL PURPOSE

------ # BITS ------











CPU Registers (Continued)

	Register	Size (Bits)	Remarks
A, A'	Accumulator	8	Stores an operand or the results of an operation
F. F'	Flags	8	See Instruction Set.
B, B'	General Purpose	8	Can be used separately or as a 16-bit register with C
C. C'	General Purpose	8	See B, above.
D. D'	General Purpose	8	Can be used separately or as a 16-bit register with E.
E. E'	General Purpose	8	See D, above
н, н'	General Purpose	8	Can be used separately or as a 16-bit register with L.
L. L'	General Purpose	8	See H, above.
			Note: The (B,C), (D,E), and (H,L) sets are combined as follows: B-High byte C-Low byte D-High byte E-Low byte H-High byte L-Low byte
I	Interrupt Register	8	Stores upper eight bits of memory address for vectored interrupt processing.
R	Refresh Register	8	Provides user-trasparent dynamic memory refresh. Lower seven bits are automatically incremented and all eight are placed on the address bus during each instruction fetch cycle refresh time.
IX	Index Register	16	Used for indexed addressing.
IY	Index Register	16	Same as IX, above.
SP	Stack Pointer	16	Holds address of the top of the stack. See Push or Pop in instruction set.
PC	Program Counter	16	Holds address of next instruction.
IFF1-IFF2	Interrupt Enable	Flip-Flops	Set or reset to indicate interrupt status (see Figure 4).
IMFa-IMFb	Interrupt Mode	Flip-Flops	Reflect Interrupt mode (see Figure 4).

Table 1. CPU Registers



Interrupts: General Operation

The CPU accepts two interrupt input signals: NMI and INT. The NMI is a nonmaskable interrupt and has the highest priority. INT is a lower priority interrupt and it requires that interrupts be enabled in software in order to operate. INT can be connected to multiple peripheral devices in a wired-OR configuration.

The Z80 has a single response mode for interrupt service for the non-maskable interrupt. The maskable interrupt, INT, has three programmable response modes available.

These are:

- Mode 0 similar with the 8080 microprocessor.
- Mode 1 Peripheral Interrupt service, for use with non-8080/Z80 systems.
- Mode 2 a vectored interrupt scheme, usually daisy-chained, for use with Z80 Family and compatible peripheral devices.

The CPU services interrupts by sampling the NMI and INT signals at the rising edge of the last clock of an instruction. Further interrupt service processing depends upon the type of interrupt that was detected. Details on interrupt responses are shown in the CPU Timing Section.

Non-Maskable Interrupt (NMI). The nonmaskable interrupt cannot be disabled by program control and therefore will be accepted at all times by the CPU. NMI is usually reserved for servicing only the highest priority type interrupts, such as that for orderly shut-down after power failure has been detected.

After recognition of the NMI signal (providing BUSREQ is not active), the CPU jumps to restart location 0066H. Normally, software starting at this address contains the interrupt service routine.

Maskable Interrupt (INT). Regardless of the interrupt mode set by the user, the Z80 response to a maskable interrupt input follows a common timing cycle. After the interrupt has been detected by the CPU (provided that interrupts are enabled and BUSREQ is not active) a special interrupt processing cycle begins. This is a special fetch (MI) cycle in which IORQ becomes active rather than MREQ, as in normal MI cycle. In addition, this special MI cycle is automatically extended by two WAIT states, to allow for the time required to acknowledge the interrupt request.

Mode 0 Interrupt Operation. This mode is similar to the 8080 microprocessor interrupt service procedures. The interrupting device places an instruction on the data bus. This is normally a Restart Instruction, which will initiate a call to the selected one of eight restart locations in page zero of memory. Unlike the 8080, the Z80 CPU responds to the Call instruction with only one interrupt acknowledge cycle followed by two memory read cycles.

Mode 1 Interrupt Operation. Mode 1 operation is very similar to that for the $\overline{\text{NMI}}$. The principal difference is that the Mode 1 interrupt has a restart location of 0038H only.

Mode 2 Interrupt Operation. This interrupt mode has been designed to utilize most effectively the capabilities of the Z80 microprocessor and its associated peripheral family. The interrupting peripheral device selects the starting address of the interrupt service routine. It does this by placing an 8-bit vector on the data bus during the interrupt acknowledge cycle. The CPU forms a pointer using this byte as the lower 8-bits and the contents of the I register as the upper 8-bits. This points to an entry in a table of addresses for interrupt service routines. The CPU then jumps to the routine at that address. This flexibility in selecting the interrupt service routine address allows the peripheral device to use several different types of service routines. These routines may be located at any available location in memory. Since the interrupting device supplies the low-order byte of the 2-byte vector, bit 0 (A_0) must be a zero.

Interrupt Priority (Daisy Chaining and Nested Interrupts). The interrupt priority of each peripheral device is determined by its physical location within a daisy-chain

Interrupts: General Operation (Continued)

configuration. Each device in the chain has an interrupt enable input line (IEI) and an interrupt enable output line (IEO), which is fed to the next lower priority device. The first device in the daisy chain has its IEI input hardwired to a High level. The first device has highest priority, while each succeding device has a corresponding lower priority. This arrangement permits the CPU to select the highest priority interrupt from several simultaneously interrupting peripherals.

The interrupting device disables its IEO line to the next lower priority peripheral until it has been serviced. After servicing, its IEO line is raised, allowing lower priority peripherals to demand interrupt servicing.

The Z80 CPU will nest (queue) any pending interrupts or interrupts received while a selected peripheral is being serviced.

Interrupt Enable/Disable Operation. Two flip-flops, IFF_1 and IFF_2 , referred to in the register description are used to signa! the

CPU interrupt status. Operation of the two flip-flops is described in Table 2. For more details, refer to the *Z80 CPU Technical Manual*.

Action	IFF ₂	IFF ₂	Comments
CPU Reset	0	0	Maskable interrupt INT disabled
DI instruction execution	0	0	Maskable interrupt INT disabled
El Instruction execution	1	1	Maskable interrupt INT enabled
LD A, I instruction execution	•	•	IFF ₂ →Parity flag
LD Å, R instruction execution	•	•	IFF2→Parity flag
Accept NMI	0	IFFi	IFF ₁ →IFF ₂ (Maskable interrupt INTdisabled)
RETN instruction execution	IFF ₂	•	IFF ₂ →IFF ₁ at completion of an NM service routine.

Table 2. State of Flip-Flops



Instruction Set

The Z80 microprocessor has one of the most powerful and versatile instruction sets available in any 8-bit microprocessor. It includes such unique operations as a block move for fast, efficient data transfers within memory or between memory and I/O. It also allows operations on any bit in any location in memory.

The following is a summary of the Z80 instruction set and shows the assembly language mnemonic, the operation, the flag status, and gives comments on each instruction. The Z80 CPU Technical Manual and Z80 CPU Programming Manual contain significantly more details for programming use.

The instructions are divided into the following categories:

- 8-bit loads
- I6-bit loads
- Exchanges, block transfers, and searches
- **B**-bit arithmetic and logic operations
- General-purpose arithmetic and CPU control

- I6-bit arithmetic operations
- Rotates and shift
- Bit set, reset, and test operations
- Jumps
- Calls, returns, and restarts
- Input and output operations

A variety of addressing modes are implemented to permit efficient and fast data transfer between various registers, memory locations, and input/output devices. These addressing modes include:

- Immediate
- Immediate extended
- Modified page zero
- Relative
- Extended
- Indexed
- D Register
- Register indirect
- Implied
- o Bit



8-Bit Load Group

Masmonic	Symbolic Operation	8	z		Fle H		P/V	H	c	Opcede 78 543 218 He		No.of M Cycles		Commonto
L) r. r'	r - r'		:	X X		X		:	:	01 r r' 00 r 110	1 2	1 2	4	<u>r, r' Reg.</u> 000 B
LD r. n	r — n	•	•	^	•	^	•	•	•	- 8 -	•	4	•	001 C
LD r. (HL)	r - (HL)	•	٠	X	٠	X	٠	٠	٠	01 r 110	L	2	7	010 D
LD r. (LX + d)	r = (lX + d)	•	•	x	•	x	•	•	•	11 011 101 DE 01 r 101) 3	5	19	011 E 100 H
Dr. (1Y+d)	$r = (\mathbf{I}\mathbf{Y} + \mathbf{d})$			x		x				- d -	3	5	19	101 L 111 A
.U P. (11 + 60	r = (11+d)	•	•	^	•	î	•	•	•	0i r i10 - d -		3		
D (HL), r	(HL) - r	•	•	X	٠	X	•	•	•	01 110 r	1	2	7	
.D (IX + d), r		•	•	X	•	X	•	•	•	11 011 101 DE 01 110 r	3	5	19	
	114 A .									-d-		5	19	
.C (iY - d), r	(l¥ + d) → r	•	•	X	•	X	•	•	•	11 111 101 FC 01 110 r - d -	3	3	19	
.D (HL), n	(HL) — n	•	•	x	•	X	٠	•	٠	00 110 110 36	2	3	01	
D (IX + d), n	(1X + d) — n	•	•	x	•	X	•	•	•	11 011 101 DC		5	19	
										- d -				
D (l¥+d), n	(IY + d) = n	•	•	x	•	x	•	•	•	11 111 101 FD 00 110 110 36	٩	5	19	
										- d - - n -				
D A. (BC)	A = (BC)	•	٠	х	•	X	٠	٠	•	00 001 010 0A	1	2	7	
D A. (DE)	A = (DE)	•	٠	X	•	X	٠	٠	٠	00 011 010 IA		2	7	
D A, (nn)	A → (nn)	•	•	x	•	X	•	•	•	00 [11 010 3A	3	4	13	
D (BC), A	(BC) - A			x		x	•		•	00 000 010 02	1	2	7	
D (DE), A	(DE) - A	•	•	Ŷ	•	х	•	•	•	00 010 010 12	i	2	÷	
ð (nn), A	(nn) - A	•	•	x	•	X	•	•	•	00 110 010 32 - n -		4	13	
D A. I	A - 1	1	:	x	٥	x	IFF	0	•	11 101 101 ED	2	2	9	
DA.R	A - R	1	:	x	0	x	IFF	0	•	01 010 111 57 11 101 101 ED	2	2	9	
DI. A.	i – A	•	•	x	•	x	•	•	•	01 011)11 SF 11 101 101 ED 01 000 111 47	2	2	9	
D R, A	R - A	٠	•	x	•	x	•	•	•	01 000 111 47 11 101 10) ED 01 001 111 4F	2	2	9	

NOTES: r. r' means any of the registery A. B. C. D. E. H. L. IFF the content of the interrupt enable flip-flip, (IFF) is copied into the PV (i.e., For er-explanation of liag neration and symbols for minimum tables, see Symbolic Nearon section to lowing tables.



16-Bit Load Group

Maamaala	Symbolic Operation			_	7	lego	P/V	X	c	76 549 210 Hen		Ho.ef M Cycles			Commonts
LD dd. na	dd - nn		•	X		_	-	•	•	00 dd0 001	3	3	10	dd	Petr
														00	BC DE
LD IX, nn	IX – na	•	٠	X	٠	X	٠	•	•	11 011 101 DD	4	4	14	10	HL
										00 100 001 21				11	SP
	W			x		x				11 111 101 FD	4	4	14		
LD IY. na	IY — na	•	•	•	•	î	•	•	•	00 100 001 21	•		••		
										- a - - a -					
LD HL. (nn)	H - (nn + 1)	•	٠	X	٠	x	٠	•	•	00 101 010 2A	3	5	16		
	L - (an)									- 4 -					
LD dd, (nn)	ddy; - (nn + 1) ddr (nn)	•	•	X	٠	x	•	•	•	11 101 101 ED 01 det1 011	4	6	20		
	00[(an)														
LD IX. (nn)	IXH - (nn+1)		•	x	•	x	•	•	•	11 011 101 DD	4	6	20		
	IXL - (nn)									00 101 010 2A		-			
										- a - - a -					
LD IY, (nn)	$\frac{11}{11} \frac{1}{11} - (nn+1)$	•	•	X	•	X	•	•	•	11 111 101 FD 00 101 010 2A	4	6	20		
	•• L = ()									- n -					
LD (nn), HL	(nn + 1) - H		•	x	•	x	•	•	•	00 100 010 22	Э	5	16		
•	(nn) — L									- a - - a -					
LD (nn), dd	(nn + 1) - ddy	•	•	x	•	x	•	•	•	11 101 101 ED	4	6	20		
	(nn) - ddL									01 dd0 01) → n ←					
									_	- n					
LD (nn), IX	(nn + 1) — IXH (nn) — IXL	•	•	x	•	x	•	•	•	11 011 101 DD 00 100 010 22	4	6	20		
	-									- n - - a -					
LD (nnl. lY	(in+1) - IYH	•	•	x	•	x	•	•	•	11 111 101 FD	4	6	20		
	(nn) - IYL									00 100 010 22 - a -					
				-		_				- n -					
ld Sp. Hl. Ld Sp. Ix	SP - HL SP - IX	:	:	X	:	X X	:	•	:	11 111 001 F9 11 011 101 DD	12	12	6 10		
LD SP. IY	SP - IY			x		x				11 111 001 F9 11 111 101 FD	2	2	10		
		•	•		-		-	•	-	11 111 001 F9				99	Pair
PUSH aq	(SP−2) – qqt (SP−1) – qqt	•	•	X	•	x	•	•	•	11 epop 101	1	3	11	90 90	DE
PUSH IX	SP - SP - 2	-						_			•			10	HL
N RUSH	(SP-2) - IXL (SP-1) - IXH	•	•	X	•	X	•	•	•	11 011 101 DD 11 100 101 ES	2	4	15	11	AF
PUSH IY	SP - SP - 2 (SP-2) - IYI			x	•	x		•		11 111 101 170	2	4	15		
	(SP-1) - IYH	-	•	^	•	î	-	-	-	11 100 101 E5	4	٩	12		
POP ag	SP - SP - 2 99H - (SP + 1)	•	•	x	•	x	•		•	11 000 001		3	10		
**	qq1 - (SP) SP - SP + 2										•	-			
OP IX	$IX_{H} = (SP + 1)$	•	•	x	•	x	•	•	•	11 011 101 DD	2	4	14		
	1X1 - (SP) SP - SP + 2									11 100 001 E1					
OP IY	$IY_H \leftarrow (SP + I)$	•	٠	x	•	x	•	•	•	11 111 101 FD	2	4	14		
	$IY_L = (SP)$ SP = SP +2									11 100 001 E1					

NOTES: dd is eny of the requirer pairs BC, DE, HL, SP, eq. is any of the requirer pairs BC, DE, HL, SP, eq. is any of the requirer pairs AF, BC, DE, HL, (PARIM), (PARIM), refer to high order and low order eight bris of the requirer pair respectively, e.g., $BC_L = C$, $AF_H = A$.



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Exchange, Block Transfer, Block Search Groups

NOTE: () If the result of B - 1 is zero the Z lieg is set, otherwise it is reset.

(2) I lieg as set upon instruction completion only



8-Bit Arithmetic and Logical Group

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(nomonic	Symbolic Operation	8	2		n I		•/1	N	c	Opcode 78 543 210 Hex	Ha.al Dytes		No.el T States	Comm	ais
ADD A. r	λ – λ + τ	1	1	X	I.	x	v	0		10 000 r	1	. É	4	r Reg.	
ADD A. n	A – A + n	1	1	X	1	X	۷	0		11 000 110	2	2	7	000 B	
										- a -				001 C	
ADD A. (HL)	A - A + (HL)			x	1	x	v	0		10 000 110		2	7	010 D 011 E	
	A = A + (DX + d)	1	1	Ŷ	;	Ŷ		ŏ	:		xo 3	-	19	100 H	
		•	•	-	•	-	•	•	•	10 000 110		-		101 L	
														m A	
ADD A, ([Y+d)	A - A + (IY + d)	1	t	X	I.	X	۷	0			FD 3) 5	19		
										10 000 110					
	A - A+s+CY			x		x	v	0		~ 💑 -				a is any of r.	. n.
	A - A-s	:	-	x		x	v	1	ì	010				(HL), (DC	
	A - A-s-CY	:	1		;	x	-	;		013				(IY + d) as for ADD :	
	A = A A 4	;		x	;	Ŷ	P		•	100				The indic	
	x - x ~ s			x	0	Ŷ	p	0	0					replace th	10 🔯 in
				x	-		p	0	0	(10) (10)				the ADD	set above.
	A-A .			•••	0	X			•						
	A-1	1	1	X	1	X	v	1	1						
	r - r + 1		1	X	1	X	v	0	•	00 r 100	1		4		
	(HL) -(HL)+1		1	X X		ž		0	•	00 110 100	DD 3	3	11 23		
	(DX+d)	1	1	X	1	X	۷	0	•	11 011 101 1 00 110 100	DD 3		23		
	(LX + d) + 1									- d -					
INC (IY + d)	(IY + d)	1	1	X	1	X	v	0	٠		FD 3	6 8	23		
	(IY+d)+1									00 110 000					
DEC m	1	,		x		x	v			- • -				-	
ULL III	m ← m − 1			•	1	•	۷	1	•	uvu				m is any of (D(+d), (

m is any of r. (HL), (IX + d). (IY + d) as shown for INC. DEC same format and states as INC. Replace [00] with [13]] in opcode.



General-Purpose Arithmetic and CPU Control Groups

Maemonic	Symbolic Operation	8	z		n #	-9-	P/ V	H	с		Dpc 545	ada 210	Hea		No.ol M Cycleo		Commente
4	Converts acc. content into packed BCD following add or subtract with peoked BCD operands.	1	1	X	1	X	P	•	1	00	100	111	27	J	1	4	Decimal adjust accumulator.
	A – X	•	•	X	1	X	•	1	•	00	101	111	2F	1	1	4	Complement accumulator (one's complement).
3	A - 0 - A	1	I	X	1	X	V	1	1			101		2	2	8	Negete acc. (two's complement).
CF	CY - CT	•	٠	X	X	X	•	0	1	00	111	111	æ	1	1	4	Complement cerry flag.
7	CY - 1	٠	٠	X	0	X	٠	0	1	00	110	111	37	1	1	4	Set carry flag.
φ.	No operation	٠	٠	X	٠	X	•	٠	٠	00	000	000	00	1	1	4	
A1.7	CPU helted	٠	٠	X	٠	X	٠	٠	•			110		1	1	4	
•	IFF - 0	٠	٠	X	٠	X	٠	٠	٠			011		1	1	4	
•	IFF - 1	٠	٠	X	٠	X	٠	٠	٠			011		1	1	4	
4.3	Set interrupt mode 0	•	•	X	٠	X	•	•	•			101		2	2	8	
M I	Set interrupt mode i	•	•	X	•	X	•	•	•			101		2	2	8	
M 2	Set interrupt mode 2	•	•	X	•	X	•	•	•			101 110		2	2	8	

SOTES IFF inductes the interrupt enable flip-flip. CY inducates the carry flip-flip. e inducates interrupts are not sampled at the end of \$1 or D1.

16-Bit Arithmetic Group

ADD HL, se	HL - HL+m	•	•	x	x	x	•	0	T	(00 4	1	0 01		ı	3	n	<u># fleg.</u> 00 BC
ADC HL, M	HL - HL+m+CY	ı	1	x	x	X	v	0	1				101 010	ED	2	4	15	01 DE 10 HL 11 SP
S3C HL. #	HL - HL - M- CY	T	1	X	X	x	V	ł	r				101 010	ED	2	4	15	11 34
ADD IX, pp	1X — IX + pp	•	•	X	x	x	•	0	ı				101 001	DD	2	4	15	pp Reg. 00 BC 01 DE 10 IX 11 SP
ADD 17, 11	IY - IY + rr	•	•	X	X	X	•	0	1				001 101	FD	2	4	15	rr Reg. 00 BC 01 DE 10 IY 11 SP
INC 88	as — as + 1	•	٠	x	٠	x	٠	•	•				011		12	1 2	6	
INC IX	IX = IX + I	•	•	X	•	X	•	•	•				101 011		2	2	10	
INC IY	IY = IY + 1	٠	•	X	•	X	٠	•	•	1	11	11		FD	2	2	10	
DEC 📾	m - m-1		•	x		x	•							2		1	6	
DEC IX	IX = IX - I	٠	٠	x	٠	x	٠	٠	٠	1	1 0)	101		12	2	ĴŌ	
DEC IY	14 - 14 - 1	•	•	x	•	X	•	•	•	1	11	11	011 101 011	FD	2	2	10	

VC1ES as is any of the requirer pairs BC, DE, NL, SP, pt is any of the requirer pairs BC, DE, IX, SP, rf is any of the requirer pairs BC, DE, IY, SP.



Rotate and Shift Group

Maomonic	Symbolic Operation	5	2		Fle H		P/V	N	c	Opcode 78 543 210	Noz		No.al M Cycles		Comments
RLCA	er	•	•	x	C	x	•	0	T	00 000 111	07	۱	ı	4	Rouse left circular accumulator.
RLA		•	•	x	0	X	•	0	1	00 010 111	17	1	1	4	Rotate left accumulator.
RRCA		•	•	x	0	x	•	0	1	00 00: 111	OF	1	1	4	Rotate right circular accumulator.
RA		•	•	x	0	x	•	0	1	00 011 111	1F	1	1	4	Rotate right ecrumulator.
RLC r)	1	1	x	0	X	P	0	1	11 003 011 00 0000 r	CB	2	2	8	Rotate leit circular register r.
ILC (HL)		ľ	ł	x	0	X	P	0	1	11 001 011 00 0000 110	C	2	4	15	<u>r Reg</u> . 000 B 001 C
NLC (UX + d)	<pre>{ CY70_ r,(HL).(IX+d),(IY+d)</pre>	1	1	x	0	X	P	0	ı	11 011 101 11 001 011 - d - 00 5555 110			6	2	010 D 011 E 100 H 101 L 111 A
NLC (17+d)	,]	1	ı	x	0	x	P	0	1	11 111 101 11 001 011 - d -	FD Ce		6	23	
l n	Cr	1 1)	ı	x	0	x	P	0	1	00 000 110 010					Instruction formet and states are as shown for RLC's. To form new
RRC m		n 1	1	X	0	X	P	0	1	[[1]					opcode replace
RR m	m=r.(HL).(IX + d).(IY + d) a)	1	x	0	x	P	0	1						
SLA m	CV		1	x	0	x	P	0	1	100					
SRA m	m=r.(HL),(IX+d),(IY+d	an I	;	x	0	x	P	0	1	Hell					
SRL m	•	1 d)	1	x	0	x	P	0	1						
RLD	7-63-9 (7-63-0 A PL	• I	ı	x	0	x	P	0	•	11 101 101 C1 101 111	ED 6F	2	5	18	Rotate digit left and right between the accumulator
RRD	7-4]3-07-4]3-0 A PIG	ים	ı	x	6	x	P	0	•	1) 101 101 01 100 111	ED 67	2	5	18	and location (HL). The content of the upper half of the eccumulator is unaflected



Bit Set, Reset and Test Group

Maemonic	Symbolic Operation	8	z		7	lage	2/1	/ 30	_c	Opcode 78 543 210 Nox		No.el M Cycles		Composis
9(T b. r	2 – n _b	x	1	x	1	x	x	0	•	11 001 011 CB 01 b r	2	2	8	r Reg. 600 B
в(? Б. (HL)	Z – (HL) _b	X	I.	X	1	X	x	C	•	11 001 011 CB 01 b 110	2	Э	12	001 C 010 D
В(Т Ь. (IX + d) _b	$z = (\overline{ix + d})_b$	x	1	x	1	x	x	C	•	11 011 101 DD 11 001 011 CB - d - 01 b 110	4	5	20	011 E 100 H 101 L 111 A b Bit Tested
8(Т b. (IY + d)b	2 – (ÎY+d)_b	X	1	X	1	X	x	0	•	11 111 1G1 FD 11 001 011 CB - d - 01 5 110	4	5	20	00 0 001 1 010 2 011 3 100 4 101 5 110 6 111 7
527 b. r .	r _b – 1	•	•	X	٠	X	٠	•	•	іі001011СВ Півг	2	2	8	
ет Б. (HL)	(HL) _b - 1	•	•	x	٠	x	٠	•	•	11 001 011 СВ П ь 110	2	4	15	
iET b. (IX + d)	$(X + d)_{\mathbf{b}} = 1$	•	•	X	•	X	•	•	•	11 011 101 DD 11 001 011 CB - d - [T] b 110	4	6	23	
SET b, (I¥+d)	$(iY+d)_{b} = 1$	•	•	X	•	X	•	•	•	11 111 101 FD 11 001 011 CB - d - П ь 110	4	6	23	
815 b, m	na _b 0 na = r.(HL), (IX + d), (IY + d)	•	•	X	•	X	•	•	•					To form new opcode replace ()) of SET b, e with ()). Plage and time states for SET instruction.

NOTES: The notation mb indicates bit b (0 to 7) or location m.

Jump Group

JP na	PC - nn	•	•	X	•	X	•	٠	•	11 000 011 C3	Э	3	10	
i? cc. nn	If condition cc is true PC — nn, otherwise continue	•	•	x	•	X	•	•	•	- a - li cc 0i0 - a - - a -	3	3	10	cc Condition 000 NZ non-zero 001 Z zero 010 NC non-carry 011 C carry 100 PO perity odd 101 PE perity even
JB •	PC - PC++	•	•	x	•	x	•	•	•	00 011 000 18	2	3	12	110 P sign positive 111 M sign negative
IR C, •	11C = 0.	•	•	x	•	X	•	٠	•	00 111 000 38	2	2	7	Il condition not met.
	continue HC = 1, PC - PC+e										2	3	12	Il condition is met.
IR NC, .	li C = 1.	•	•	X	٠	X	•	•	•	00 110 000 30	2	2	7	Il condition not met.
	LIC = 0. PC - PC+e									- • •	2	3	12	If condition is met.
IP Z. •	lf Z = 0 continue	•	٠	X	٠	X	٠	٠	•	00 101 000 28	2	2	7	If condition not met.
	If Z = 1, PC - PC++										2	3	12	B condition is met.
18 NZ. •	$\frac{1}{2} = 1.$	•	•	X	•	X	•	٠	•	00 100 000 20 - e-2 -	2	2	7	Il condition not met.



Jump Grup (Continued)

.

Masmoale	Symbolic Operation	\$	2		Fle X	ige	P/ ¥	H	с	Opco 78 543	10 210	Hez	No.ol Byree	No.of M Cysles	No.el T States	Comments
	continue Li Z = 0, PC - PC + e												2	Э	12	li condition is met.
JP (HL)	PC - HL	•	•	X	•	X	•	٠	٠	11 101	001	E9	1	1	4	
IP (IX)	PC - IX	•	•	X	•	X	•	•	•	11 011 11 101			2	2	8	
JP (IY)	PC - 11		•		•	X	•	•	٠	11 111 11 101			2	2	8	
DINZ, •	8 - 8 - 1 lí 8 = 0. continue	•	•	X	•	X	•	•	•	00 010	000		2	2	•	14 B = 0.
	11 B ≠ 0, PC - PC+e												2	3	13	ii B ≠ 0.

NOTES: e rep nte the in the relative add

ive addressing mode. In the range < -126, 129 >, we address of pc+o as PC is incre is a signed two's compleme = 2 in the opcode provides by 2 prior to the addition

Call and Return Group

CALL m	(SP - 1) - PCH ISP - 2) - PCL PC - nn	•	•	X	•	x	•	•	•	11 001 101 CD	3	5	17	
CALL cc. an	li condition cc is false	•	•	X	•	x	•	•	•	11 cc 100	3	3	10	II cc is felse.
	continue, otherwise same as CALL nn									- a -	3	5	17	li cc is true.
RET	PCL - (SP) PC _H - (SP+1)	•	•	X	٠	X	•	٠	٠	11 001 001 C9	1	3	ю	
RET cc	li condition oc is false	•	•	X	٠	X	٠	•	٠	11 cc 000	L	1	5	If oc to false.
	continue, otherwise										I	3	n	If oc as true.
	same as RET													oc Condition 000 NZ non-zero 001 Z sero
RETI	Return from	•	•	X	•	X	•	•	•	11 101 101 ED 01 001 101 4D	2	4	14	010 NC non-carry 011 C carry
RETNI	Return from non-mascable interrupt	•	•	X	•	x	•	•	•	11 101 101 ED 01 000 101 45	2	4	14	100 PO parity odd 101 PE parity even 110 P sign positive 111 M sign negative
RST p	(SP - 1) - PCH (SP - 2) - PCL PCH - 0 PCL - P	•	•	X	•	x	•	•	•	11 + 111	J	3	41	t p 000 00H 001 00H 010 10H 010 10H 010 10H 101 20H 101 20H 101 20H 101 30H



Input and Output Grup

Masmonic	Symbolic Operation	8	2		Fig H		P/V	N	c	Opcode 76 543 210 Hex	Ha.al Bytes	No.al M M Cycles 1		Comments
IN A. (n)	A - (n)	•	•	x	•	x	•	•	•	11 011 011 DE	3 2	3	11	n to Ao - A7
							-					3		Acc. to Ag - A15
(C) r. (C)	r (C) tir = 110 only the	1	1	x	1	X	P	0	•	11 101 101 EE 01 7 000	2	3	12	C to Ag - A7 B to Ag - A15
	flags will be affected		0											• ••
IN!	(HL) - (C)	x	Ť	x	x	x	x	1	x	11 101 101 EL	2	4	16	C to Ag - A7
L.1	B - B-1	-	-							10 100 010 A	2			B to Ag - A15
INIR	HL = HL + 1 $(HL) = (C)$	x	1	x	x	x	x	1	x	11 101 101 EE	2	5	2!	C to Ag ~ A7
2918	B - B - 1	-	•	• ••	-	~	•	·		10 110 010 B	2	(∐ B≠0)		B to Ag - A15
	HL - HL + 1 Repeat until										2	4 (HB=0)	16	
	B = 0		0											
IND	(HL) - (C)	X	-	x	x	X	X	1	X	11 101 101 ED		4	16	C to Ao - A7
	B - B -1									10 101 010 AJ	۱			B to Ag - A15
NOR	HL - HL - 1 (HL) - (C)	¥	1	¥	¥	x	x	ı	X.	11 101 101 EC	> 2	5	21	C to Ag ~ A7
N JR	B = B - 1	^		^	^	^	^	•		10 111 010 B/		(If B≠0)		B to An - Ais
	HL – HL – 1 Repeat until										2	4 (ビヨ=0)	16	
OUT (n), A	B = 0 (n) - A	•		x		x			•	11 010 011 D	3 2	3	11	n 10 Ag - A7
										- 6 -				Acc. to Ag - A15
OUT (C), r	(C) - r	٠	•	X	•	X	•	•	•	11 101 101 EI	> 2	Э	12	$C to A_0 - A_7$
			Φ							0] r 001				B to Ag - A15
OUTI	(C) - (HL)	X	ĩ	X	,х	X	X	1	X	11 101 101 E	> 2	4	16	C to Ag ~ Ag
	B - B-1									10 100 011 A	3			B to A8 - A15
OTIR	HL = HL + 1 $(C) = (HL)$	¥	1	Y	¥	¥	x	,	x	11 101 101 E	2	5	21	C to Ag - A7
w · 10	(C) = (RL) B = B = 1		•	^	Ŷ	^	~	•	^	10 110 011 B		(UB+0)		8 to Ag - A15
	HL = HL + 1										2	4	16	• ••
	Repeat until											(II B = 0)		
	B = 0		0											
OUTD	(C) - (HL)	x	ĭ	X	X	X	X	1	X	11 101 101 EI		4	16	C to Ag - A7
	B - B-1									10 101 011 A	B			B to Ag - A15
	HL - HL-)		_											
0708		-	ą			-	x		x	11 101 101 E	2	5	2)	C to A0 - A7
OTDR	(C) (HL) B B 1	X	I	X	X	¥	X	+	x	10 111 011		(11 8=0)	•,	B to Ag - A15
	HL - HL-1										2	4	16	
	Repeat until B = 0											(11 3 = 0)		

NOTE II the result of B-1 is sero the Z flag is set, otherwise it is reset.



Summary of Flag Operation

Symbol

Instruction	Dy S	2		Ħ		2/ 4	N	De C	Comments
ADD A. s: ADC A. s	1	1	X	ı	x	٧	0	1	8-but add or add with carry.
SUB s: SBC A s: CP s: NEG	1	1	X	1	X	۷	1	1	8-bit subtract, subtract with carry, compare and negate accumulator.
AND .		1	X X X	1	X	P	0	8	Logical operations.
OR s, XOR s		1		0	x	P	0	01	• •
NC •	1	1	X	1	X	۷	0	•	8-bit increment.
DEC .		1	X	1	x	v	1	•	8-bit decrement.
NDD DD, 🖬	•	٠	X	x	x	•	0	1	16-bit edd.
ADC HL, m	1	1	x	x	x	۷	0	1	16-bit edd with cerry.
BC HL, se	1	1	x	X	X	Ŷ	L	1	16-bit subtract with carry.
ILA, RLCA, RRA; RRCA	•	٠	X	0	x	•	0	1	Rotate accumulator.
LL m; RLC m; AR m; RRC m; SLA m; SRA m; SRL m	:	ı	X	0	X	P	0	1	Roters and shift locations.
LD: RRD	1	1	x	٥	x	P	0	•	Rotate digit left and right.
AA	i	1	X	1	X	P	٠	1	Decimel ediust eccumulator.
PL	•	•	X	i.	X	•	1	•	Complement accumulator.
CT	٠	٠	x	0	X	•	Ó	1	Set carry.
CF	٠	٠	X	X	X	•	0		Complement carry.
Nr(C)	1	1	X	0	X	P	0	•	Input register indirect.
NI, IND, OUTI: OUTD NIR; INDR; OTIR; OTDR	X	1	X	X	X X	X X	1	:}	Block input and output, $Z = 0$ if $B \neq 0$ otherwise $Z = 0$.
DI: LDD	X X	1 X	X X	X	Ŷ	î	ò		
DIR: LDDR	Ŷ	Ŷ	Ŷ	ŏ	Ŷ	ò	ŏ		Block transfer instructions, P/V = 1 if BC # 0, otherwise P/V = 0.
PI: CPIA; CPD: CPDA	Ŷ	î	Ŷ	x	Ŷ	ĩ	ĩ	•	Block search instructions. Z = I sl A = (HL), otherwise Z = 0. P/V = I tl BC = 0. otherwise P/V = 0.
DA. I. LDA. R		1	X	0	x	IFF	0 . The content of the interrupt enable flip-flop (IFF) is copied into the P/V flag		
NT b. e	Ŷ.	1	X	1	X	X	X 0 • The state of bit b of location s is copied into the Z flag.		

Symbol

Operation

S	Sign flag. $S = 1$ if the MSB of the result is 1.
Z	Zero flag. $Z = 1$ if the result of the operation is 0.
P/V	Parity or overflow flag. Parity (P) and overflow
	(V) share the same flag. Logical operations affect
	this flag with the parity of the result while
	arithmetic operations affect this flag with the
	overflow of the result. If P/V holds parity, P/V =
	I if the result of the operation is even, $P/V = 0$ if
	result is odd. If P/V holds overflow, $P/V = 1$ if
	the result of the operation produced an overflow.
н	Half-carry flag. $H = 1$ if the add or subtract
••	operation produced a carry into or borrow from
	bit 4 of the accumulator.
N	Add/Subtract flag. $N = 1$ if the previous opera-
14	tion was a subtract. $N = 1$ if the previous operation was a subtract.
	tion was a subtract.

- H & N H and N flags are used in conjunction with the decimal adjust instruction (DAA) to properly correct the result into packed BCD format following addition or subtraction using operands with packed BCD format.
- C Carry/Link flag. C = 1 if the operation produced a carry from the MSB of the operand or result.

1 The flag is affected according to the result of the operation. . The flag is unchanged by the operation. 0 The flag is reset by the operation. 1 The flag is set by the operation. X The flag is a "don'i care." v P/V flag affected according to the overflow result of the operation. Ρ P/V flag affected according to the parity result of the operation. Any one of the CPU registers A, B, C, D, E, H, L. r .

Operation

- Any 8-bit location for all the addressing modes allowed for the particular instruction.
- Any 16-bit location for all the addressing modes allowed for that instruction.
- ii Any one of the two index registers IX or IY.
- R Refresh counter.
- n 8-bit value in range < 0, 255 >.
- nn 16-bit value in range < 0, 65535 >.

Z8400

Pin Descriptions

A₀-A₁₅. Address Bus (output, active High, 3-state). A₀-A₁₅ form a 16-bit address bus. The Address Bus provides the address for memory data bus exchanges (up to 64K bytes) and for I/O device exchanges. **BUSACK**. Bus Acknowledge (output, active Low). Bus Acknowledge indicates to the requesting device that the CPU address bus, data bus, and control signals MREQ, IORQ, RD, and WR have entered their highimpedance states. The external circuitry can now control these lines.

BUSREQ. Bus Request (input, active Low). Bus Request has a higher priority than NMI and is always recognized at the end of the current machine cycle. BUSREQ forces the CPU address bus, data bus, and control signals MREQ, IORQ, RD, and WR to go to a high-impedance state so that other devices can control these lines. BUSREQ is normally wire-ORed and requires an external pullup for these applications. Extended BUSREQ periods due to extensive DMA operations can prevent the CPU from properly refreshing dynamic RAMs.

D₀-**D**₇. Data Bus (input/output, active High, 3-state). D₀-D₇ constitute an 8-bit bidirectional data bus, used for data exchanges with memory and I/O.

HALT. Halt State (output, active Low). HALT indicates that the CPU has executed a Halt instruction and is awaiting either a nonmaskable or a maskable interrupt (with the mask enabled) before operation can resume. While halted, the CPU executes NOPs to maintain memory refresh.

INT. Interrupt Request (input, active Low). Interrupt Request is generated by I/O devices. The CPU honors a request at the end of the current instruction if the internal software-controlled interrupt enable flip-flop (IFF) is enabled. INT is normally wire-ORed and requires an external pullup for these applications.

IORQ. Input/Output Request (output, active Low, 3-state). IORQ indicates that the lower half of the address bus holds a valid I/O address for an I/O read or write operation. IORQ is also generated concurrently with MI during an interrupt acknowledge cycle to indicate that an interrupt response vector can be placed on the data bus.

MI. Machine Cycle One (output, active Low). MI, together with MREQ, indicates that the current machine cycle is the opcode fetch cycle of an instruction execution. MI, together with IORQ, indicates an interrupt acknowledge cycle.

MREQ. Memory Request (output, active Low, 3-state). MREQ indicates that the address bus holds a valid address for a memory read or memory write operation.

NMI. Non-Maskable Interrupt (input, negative edge-triggered). NMI has a higher priority than INT. NMI is always recognized at the end of the current instruction, independent of the status of the interrupt enable flip-flop, and automatically forces the <u>CP</u>U to restart at location 0066H.

RD. Read (output, active Low, 3-state). RD indicates that the CPU wants to read data from memory or an I/O device. The addressed I/O device or memory should use this signal to gate data onto the CPU data bus.

RESET. Reset (input, active Low). RESET initializes the CPU as follows: it resets the interrupt enable flip-flop, clears the PC and Registers I and R, and sets the interrupt status to Mode 0. During reset time, the address and data bus go to a highimpedance state, and all control output signals go to the inactive state. Note that RESET must be active for a

minimum of three full clock cycles before the reset operation is complete.

RFSH. Refresh (output, active Low). RFSH, together with MREQ, indicates that the lower seven bits of the system's address bus can be used as a refresh address to the system's dynamic memories.

WAIT. Wait (input, active Low). WAIT indicates to the CPU that the addressed memory or I/O devices are not ready for a data transfer. The CPU continues to enter a Wait state as long as this signal is active. Extended WAIT periods can prevent the CPU from refreshing dynamic memory properly. WR. Write (output, active Low, 3-state). WR indicates that the CPU data bus holds valid data to be stored at the addressed memory or I/O location.



CPU Timing

The Z80 CPU executes instructions by proceeding through a specific sequence of operations:

- Memory read or write
- I/O device read or write
- Interrupt acknowledge

The basic clock period is referred to as a T time or cycle, and three or more T cycles make up a machine cycle (M1, M2 or M3 for instance). Machine cycles can be extended either by the CPU automatically inserting one or more Wait states or by the insertion of one or more Wait states by the user.

Instruction Opcode Fetch. The CPU places the contents of the Program Counter (PC) on the address bus at the start of the cycle (Figure 5). <u>Approximately one-half clock</u> cycle later, MREQ goes active. When active, RD indicates that the memory data can be enabled onto the CPU data bus.

The CPU samples the WAIT input with the falling edge of clock state T_2 . During clock states T_3 and T_4 of an $\overline{M1}$ cycle dynamic RAM refresh can occur while the CPU starts decoding and executing the instruction. When the Refresh Control signal becomes active, refreshing of dynamic memory can take place.



NOTE: Tw-Wait cycle added when necessary for slow ancilliary devices.



Memory Read or Write Cycles. Figure 6 shows the timing of memory read or write cycles other than an opcode fetch (MI) cycle. The MREQ and RD signals function exactly as in the fetch cycle. In a memory write cycle, \overline{MREQ} also becomes active when the address bus is stable. The \overline{WR} line is active when the data bus is stable, so that it can be used directly as an R/\overline{W} pulse to most semiconductor memories.



Figure 6. Memory Read or Write Cycles



Input or Output Cycles. Figure 7 shows the timing for an I/O read or I/O write operation. During I/O operations, the CPU automatically inserts a single Wait state (T_w) .

This extra Wait state allows sufficient time for an I/O port to decode the address from the port address lines.



NOTE. Tw- = One Wait cycle automatically inserted by CPU.

Figure 7. Input or Output Cycles



Interrupt Request/Acknowledge Cycle. The CPU samples the interrupt signal with the rising edge of the last clock cycle at the end of any instruction (Figure 8). When an interrupt is accepted, a special MI cycle is generated.

During this $\overline{M1}$ cycle, \overline{IORQ} becomes active (instead of \overline{MREQ}) to indicate that the interrupting device can place an 8-bit vector on the data bus. The CPU automatically adds two Wait states to this cycle.



NOTE: 1) TL = Last state of previous instruction.

2) Two Wait cycles automatically inserted by CPU(*).

Figure 8. Interrupt Request/Acknowledge Cycle



Non-Maskable Interrupt Request Cycle. NMI is sampled at the same time as the maskable interrupt input INT but has higher priority and cannot be disabled under software control. The subsequent timing is similar to that of a normal instruction fetch except that data put on the bus by the memory is ignored. The CPU instead executes a restart (RST) operation and jumps to the <u>NMI</u> service routine located at address 0066H (Figure 9).



*Although NMI is an asynchronous input, to guarantee its being recognized on the following machine cycle, NMI's falling edge

must occur no later than the rising edge of the clock cycle preceding $T_{\mbox{LAST}}$

Figure 9. Non-Maskable Interrupt Request Operation



Bus Request/Acknowledge Cycle. The CPU samples BUSREQ with the rising edge of the last clock period of any machine cycle (Figure 10). If BUSREQ is active, the CPU sets its address, data, and MREQ, IORQ, RD, and \overline{WR} lines to a high-impedance state with the rising edge of the next clock pulse. At that time, any external device can take control of these lines, usually to transfer data between memory and I/O devices.



NOTE: T_L = Last state of any M cycle.

Tx = An arbitrary clock cycle used by requesting device.

Figure 10. Z-Bus Request/Acknowledge Cycle



Halt Acknowledge Cycle. When the CPU receives an Halt instruction, it executes NOP states until either an INT or NMI input is received. When in the Halt state, the HALT output is active and remains so until an interrupt is received (Figure 11).

Reset Cycle. RESET must be active for at least three clock cycles for the CPU to

properly accept it. As long as RESET remains active, the address and data buses float, and the control outputs are inactive. Once RESET goes inactive, three internal T cycles are consumed before the CPU resumes normal processing operation. RESET clears the PC register, so the first opcode fetch will be to location 0000 (Figure 12).



NOTE: INT will also force a Halt exit.

*See note, Figure 9.





Figure 12. Reset Cycle

AC Characteristics

			Z8 4		Z84	A00	Z84	008	Z84	00H
Number	Symbol	Parameter	Min (ns)	Max (ns)	Min (ns)	Max (ns)	Min (ns)	Max (ns)	Min (ns)	Max (ns)
1	ToC	Clock Cycle Time	400°		250°		165*		125*	
2	TwCh	Clock Pulse Width (High)	180*	_	110*	_	65°	_	55°	
3	TwCi	Clock Pulse Width (Low)	180	2000	110	2000	65	2000	55	2000
4	TÍC	Clock Fall Time	• • • •	30	_	30	_	20	_	10
5	-TrC	- Clock Rise Time		30		30				l0
6	TdCr(A)	Clock 1 to Address Valid Delay	_	145	_	110	_	90	_	80
7	TdA(MREQf)	Address Valid to MREQ 4 Delay	125*	_	65 *	_	35*	_	20•	_
8	TdCI(MREQf)	Clock I to MREQ I Delay	-	100	_	85	_	70	_	60
9	TdCr(MREQr)	Clock † to MREQ † Delay	-	100	_	85	—	70	_	60
10	-TwMREQh	- MREQ Pulse Width (High)	- 170* -		-110*-		- 65*-		- 45*-	
11	TwMREQ	MREQ Pulse Width (Low)	360*	_	220°	_	135*	_	100*	_
12	TdCI(MREQr)	Clock ↓ to MREQ ↑ Delay	_	100	_	85	_	70	—	60
13	TdCi(RDi)	Clock \downarrow to $\overline{RD} \downarrow$ Delay	—	130	-	95	-	80	_	70
14	TdCr(RDr)	Clock f to RD f Delay	_	100	_	85	_	70	_	60
	- TsD(Cr)	-Data Setup Time to Clock 1	- 50 -		- 35 -		- 30 -		- 30 -	
16	ThD(RDr)	Data Hold Time to RD 1	_	0	_	0	_	0	_	0
17	TsWAIT(Cf)	WAIT Setup Time to Clock 4	70	—	70	-	60	-	50	—
18	ThWAIT(Cf)	WAIT Hold Time after Clock 1	—	0	-	0	-	0	-	0
19	TdCr(MIP	Clock † to MI ↓ Delay	-	130	_	100	_	80	_	70
20	- TdCr(M:::)	-Clock † to MI † Delay		- 130 ·		-100-				70
21	TdCr(RFSHf)	Clock † to RFSH ↓ Dealy	—	180	—	130	-	110	-	95
22	TdCr(RFSHr)	Clock † to RFSH † Delay	-	150	—	120	-	100	-	85
23	TdCf(BD=)	Clock 1 to RD † Delay	-	110	—	85	-	70	-	60
24	TdCr(BC:)	Clock † to RD ↓ Dealy	-	110	_	85	-	70	—	60
25	– TsD(Cı` ———	- Data Setup to Clock ↓ during — M ₂ , M ₃ , M ₄ or M ₅ Cycles	—6 0 —		- 50		- 40 -		- 30	
26	TdA(ICEQI)	Address Stable prior to IORQ 1	320*	—	180°	_	110*	_	75 *	
27	TdCr(ICRQf)	Clock † to IORQ ↓ Delay	_	90	_	75	_	65	_	55
28	TdCt(ICEQr)	Clock 1 to IORQ † Delay	_	110	_	85	_	70	—	60
29	TdCt(WEi)	Data Stable prior to WR J	190*	_	80*	_	25°	_	5*	_
30	_TdDf(WEi)	-Clock ↓ to WR ↓ Delay		90 -				70		60
31	TwWR	WR Pulse Width	360*		220°	_	135*	_	100*	_
32	TdCh(WEr)	Clock↓ to WR↑ Delay	_	100	_	80	—	70	_	60
33	TdD(WE:)	Data Stable prior to WR 4	20*	_	·10*	_	-55*	_	55*	
34	TdCr(WRf)	Clock † to WR ↓ Delay	_	80	—	65	_	60		55
35	TdWE: D)	Data Stable from WR 1	120*		60°		30°		15*	_

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For clock periods either than the minimums shown in the table, calculate parameters using the expressions in the table on the following page.
 All timings are preliminary and subject to change.

AC Characteristics (Continued)

		28400			284	A00		100B	Z8400H	
Number	Symbol	Parameter	Min (ns)	Max (ns)	Min (ns)	Max (ns)	Min (ns)	Max (ns)	Min (ns)	Max (ns)
36	TdCi(HALT)	Clock 1 to HALT † or 1	_	300		300		260	-	225
37	TwNMI	NMI Pulse Width	80	_	80	_	70	-	60°	-
38	TsBUSREQ(Cr)	BUSREQ Setup Time to Clock 1	80	_	50	_	50	-	40	-
39	TcBUSUREQ(Cr)	BUSREQ Hold Time after Clock 1	0	_	0	-	0	_	0	-
40	- TdCr(BUSACKi)	Clock † to BUSACK ↓ Delay		- 120 -		- 100 -		- 90 -		- 80
41	TdCf(BUSACKr)	Clock 1 to BUSACK † Delay	_	110	_	100	_	90		80
42	TdCr(Tz)	Clock † to Data Float Delay	_	90	_	90	_	80	_	70
43	TdCr(CTz)	Clock † to Control Outputs Float Delay (MREQ, IORQ, RD, and WR)	-	110	-	80	-	70	-	60
44	TdCr(Az)	Clock 1 to Address Float Delay	_	110	_	90	_	80	_	70
45	- TdCTr(A)	MREQ 1, IORQ 1, RD 1, and WR 1 to Address Hold Time	- 160*-		- 80'-		35*		- 20:	
46	TsRESET(Cr)	RESET to Clock † Setup Time	90	_	60	_	60		45	_
47	ThRESET(Cr)	RESET to Clock † Hold Time	_	0	_	0	_	0	_	0
48	TsINTi(Cr)	INT to Clock † Setup Time	80	—	80	-	70	_	55	_
49	ThiNTr(Cr)	INT to Clock † Hold Time	_	0	_	0	_	0	_	0
50	-TdMlf(IORQf)	-MI 1 to IORQ 1 Delay	-920*-		- 565*-		-365*-		-270*-	
51	TdCI(IORQI)	Clock ↓ to IORQ ↓ Delay	_	110	_	85	-	70	_	60
52	TdCl(IORQr)	Clock † to IORQ † Delay	-	100	_	85	_	70	_	60
53	TdCI(D)	Clock 4 to Data Valid Delay	_	230		150	_	130	_	115

* For clock periods other than the minimums shown in the table, calculate parameters using the expressions in the table on the following page. All timings are preliminary and subject to change.



Number	Symbol	Z8400	Z8400A	Z8400B
1	TeC	TwCh + TwCl + TrC + TfC	TwCh + TwCl + TrC + TfC	TwCh+TwCl+TrC+TfC
2	TwCh	Although static by design,	Although static by design,	Although static by design
		TwCh of greater than	TwCh of greater than	TwCh of greater than
		200 µs is not guaranteed	200 µs is not guaranteed	200 µs is not guaranteed
7	- TdA(MREQI) —	- TwCh + TfC - 75	- TwCh + TfC - 65	- TwCh + TfC - 50
10	TwMREQh	TwCh + TIC - 30	TwCh + TfC - 20	TwCh + TfC - 20
11	TwMREQI	TcC - 40	TcC – 30	TcC-30
26	TdA(IORQf)	TcC - 80	TcC - 70	TcC - 55
29	TdD(WRf)	TcC-210	TcC - 170	TcC - 140
31	- TwWR	- TcC - 40	- TcC - 30	- TcC - 30
33	TdD(WRf)	TwCl + TrC - 180	TwCl + TrC - 140	TwC1 + TrC - 140
35	TdWRr(D)	TwCl+TrC-80	TwCl + TrC - 70	TwCl+TrC-55
45	TdCTr(A)	TwCl + TrC - 40	TwCl+TrC-50	TwCl+TrC-50
50	TdMlf(IORQf)	2TcC + TwCh + TfC - 80	2TcC + TwCh + TfC - 65	2TcC + TwCh + TfC - 50
C Test Condi V _{IH} = 2.0 V	tions:	V _{ILC} = 0.45 ↓ V _{OH} = 2.0 V		
V _{1L} = 0.8 V V _{1HC} = V _{CC} -	-06 V	V _{OL} =0.8 V FLOAT=±0.5 V		

Footnotes to AC Characteristics

Absolute Maximum Ratings

Storage Temperature65°C to +150°C
Temperature
under Bias Specified operating range
Voltages on all inputs and outputs
with respect to GND0.3 V to +7.0 V
Power Dissipation 1.5 W

Stresses greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only: operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Standard Test Conditions

The characteristics below apply for the following standard test conditions, unless otharwise noted. All voltages are referenced to GND (0 V). Positive current flows into the referenced pin. Available operating temperature ranges are:

- 0°C to +70°C, +4.75 V \leq V_{CC} \leq +5.25 V
- -40°C to +85°C,
 +4.75 V ≤ V_{CC} ≤ +5.25 V
- -55°C to +125°C, +4.75 V ≤ V_{CC} ≤ +5.25 V

All ac parameters assume a load capacitance of 50 pF. Add 10 ns delay for each 50 pF increase in load up to a maximum of 200 pF for the data bus and 100 pF for address and control lines.





DC Characteristics

Symbol	Parameter	Min.	Max	Unit	Test Condition
VILC	Clock Input Low Voitage	-0.3	0.45	v	
VIHC	Clock Input High Voltage	$V_{\rm CC} = 0.6$	V _{CC} +0.3	V	
VIL	Input Low Voltage	-0.3	0.8	V	
v _{IH}	Input High Voltage	2.0	Vcc	V	
VOL	Output Low Voltage		0.4	V	l _{OL} = 1.8 mÅ
V _{OH}	Output High Voltage	2.4		V	$I_{OH} = -250 \ \mu \text{Å}$
ICC	Power Supply Current				
-	Z8 0		150	mА	
	290 A		200 ²	mА	
	280B		200	mÅ	
	290H		200	mА	
ILI	Input Leakage Current	_	10	µA	$V_{IN} = 0$ to V_{CC}
ILO	3-State Output Leakage Current in Ficat	- 10	10 ²		VOUT = 0.4 to VCC

Capacitance

Symbol	Parameter	Min.	Max	Unit	Note
CCLOCK	Clock Capacitance		35	pF	
CIN	Input Capacitance		5	pł	Unmeasured pins returned to ground
COUT	Output Capacitance		10	pF	

 $T_A = 25^{\circ}C$, f = 1 MHz



Ordering Information

$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	Туре	Package	Temp.	Clock	Description
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	23400 B1	Plastic	0/+70°C		280 Central Processing Unit
22400 FI Frit Seal $0' + 70^{\circ}C$ 22400 D1 Ceramic $-40' + 85^{\circ}C$ 23400 D2 Ceramic $-55' + 125^{\circ}C$ 23400 C1 Plastic Chip-Carrier $0' + 70^{\circ}C$ 23400 C6 Plastic Chip-Carrier $0' + 70^{\circ}C$ 23400 C6 Plastic Chip-Carrier $-40' + 85^{\circ}C$ 23400 C ceramic Chip-Carrier $-40' + 85^{\circ}C$ 23400 K2 Ceramic Chip-Carrier $-40' + 85^{\circ}C$ 23400 K2 Ceramic Chip-Carrier $-40' + 85^{\circ}C$ 23400 K2 Ceramic $-40' + 85^{\circ}C$ 23400 K2 Ceramic $-40' + 85^{\circ}C$ 23400 C Ceramic $-40' + 85^{\circ}C$ 23400 N1 Ceramic Chip-Carrier $-40' + 85^{\circ}C$	Z3400 B6	Plastic	- 40/ + 85°C	1	
2_{2400} F6 Frit Seal $-40/+85^{\circ}C$ $0/+70^{\circ}C$ 23400 D2 Ceramic $-40/+85^{\circ}C$ 2.5 MHz 23400 D2 Ceramic $-55/+125^{\circ}C$ 2.5 MHz 23400 C6 Plastic Chip-Carrier $0/+70^{\circ}C$ 2.5 MHz 23400 K2 Ceramic Chip-Carrier $0/+70^{\circ}C$ 2.5 MHz 23400 K2 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 2.5 MHz 23400 K2 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 2.5 MHz 23400 K2 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 2.5 MHz $23400A$ F6 Frit Seal $0/+70^{\circ}C$ $23400A$ 2.6 ramic $-40/+85^{\circ}C$ $23400A$ D2 Ceramic $-55/+125^{\circ}C$ 4.0 MHz 4.0 MHz $23400A$ D2 Ceramic Chip-Carrier $0/+70^{\circ}C$ $23400A$ $2.6 \text{ ramic} Chip-Carrier -40/+85^{\circ}C 4.0 \text{ MHz} 4.0 \text{ MHz} 23400A C Ceramic Chip-Carrier -40/+85^{\circ}C 4.0 \text{ MHz} 6.0 \text{ MHz} <$		Frit Seal	0/+70°C	}	
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$		Frit Seal	-40/+85°C		
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$		Ceramic	0/+70°C		
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$		Ceramic	-40/+85°C		
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$		Ceramic	-55/+125°C	2.5 MHz	
$\begin{array}{cccccccccccccccccccccccccccccccccccc$	75400 C1	Plastic Chip-Carrier	0/+70°C		
$\begin{array}{cccccccccccccccccccccccccccccccccccc$		Plastic Chip-Carrier	- 40/ + 85°C		
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$		Ceramic Chip-Carrier	0/+70°C	1	
23400 K2 Coramic Chip-Carrier $-55/+125^{\circ}C$ 23400 B1 Plastic $0/+70^{\circ}C$ 23400 Fit Select $-40/+85^{\circ}C$ 23400 F6 Frit Seal $0/+70^{\circ}C$ $23400A$ F6 Frit Seal $0/+70^{\circ}C$ $23400A$ Ceramic $0/+70^{\circ}C$ $23400A$ Ceramic $-40/+85^{\circ}C$ $23400A$ Ceramic $-55/+125^{\circ}C$ $23400A$ Plastic Chip-Carrier $0/+70^{\circ}C$ $23400A$ Ceramic Chip-Carrier $0/+70^{\circ}C$ $23400A$ Ceramic Chip-Carrier $-40/+85^{\circ}C$ $23400A$ Ceramic Chip-Carrier $-40/+85^{\circ}C$ $23400A$ Ceramic Chip-Carrier $-40/+85^{\circ}C$ $23400A$ K1 Ceramic Chip-Carrier $-40/+85^{\circ}C$ $23400B$ Plastic $-40/+85^{\circ}C$ $-40/+85^{\circ}C$ $23400B$ Ceramic $0/+70^{\circ}C$ 6.0 MHz $23400B$ Ceramic Chip-Carrier $0/+70^{\circ}C$ 6.0 MHz $23400B$ Ceramic Chip-Carrier $0/+70^{\circ}C$ 6.0 MHz		•	- 40/ + 85°C	1	
$ \begin{array}{rrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrr$		Ceramic Chip-Carrier	-55/+125°C		
$ \begin{array}{rrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrrr$	ZS+00A B1	Plastic	0/+70°C		
28400A F6 Frit Sait $-40/+85^{\circ}C$ 28400A D1 Ceramic $0/+70^{\circ}C$ 28400A D2 Ceramic $-40/+85^{\circ}C$ 28400A D2 Ceramic $-55/+125^{\circ}C$ 28400A D2 Ceramic $-55/+125^{\circ}C$ 28400A C6 Plastic Chip-Carrier $0/+70^{\circ}C$ 28400A C6 Plastic Chip-Carrier $-40/+85^{\circ}C$ 28400A C6 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400A C6 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400A C6 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400B F1 Fit Seal $0/+70^{\circ}C$ 28400B F6 Frit Seal $0/+70^{\circ}C$ 28400B F1 F1 F1 28400B Ceramic $-55/+125^{\circ}C$ 28400B Ceramic $0/+70^{\circ}C$ 28400B Ceramic $-40/+85^{\circ}C$ 28400B Ceramic $-40/+85^{\circ}C$ 28400B Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400B Ceramic		Plastic	- 40/ + 85°C	1	
23:400.A F6 Frit Seat $-40/+85^{\circ}C$ 23:400.A D1 Ceramic $0/+70^{\circ}C$ 23:400.A D2 Ceramic $-40/+85^{\circ}C$ 23:400.A C1 Plastic Chip-Carrier $0/+70^{\circ}C$ 23:400.A C6 Plastic Chip-Carrier $0/+70^{\circ}C$ 23:400.A C6 Plastic Chip-Carrier $0/+70^{\circ}C$ 23:400.A K1 Ceramic Chip-Carrier $0/+70^{\circ}C$ 23:400.A K6 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 23:400.A K2 Caramic Chip-Carrier $-55/+125^{\circ}C$ 23:400.B K2 Ceramic $0/+70^{\circ}C$ 23:400.B F6 Frit Seal $0/+70^{\circ}C$ 23:400.B F6 Frit Seal $-40/+85^{\circ}C$ 23:400.B F6 Frit Seal $-40/+85^{\circ}C$ 23:400.B F6 Frit Seal $-40/+85^{\circ}C$ 23:400.B C1 Plastic Chip-Carrier $0/+70^{\circ}C$ 23:400.B C2 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 23:400.B C1 Plastic Chip-Carrier $-40/+85^{\circ}C$ 23:400.B K1 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 23:400.B K2 Ceramic Chip-Carrier $-40/+85^{\circ}C$		Frit Seal			
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$		Frit Seal	- 40/ + 85°C		
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$					
28400A D2Ceramic $-55/+125^{\circ}C$ 4.0 MHz28400A C1Plastic Chip-Carrier $0/+70^{\circ}C$ $2400A C6$ Plastic Chip-Carrier $-40/+85^{\circ}C$ 28400A K1Ceramic Chip-Carrier $-40/+85^{\circ}C$ $28400A K2$ Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400A K2Ceramic Chip-Carrier $-40/+85^{\circ}C$ $28400A K2$ Ceramic Chip-Carrier $-55/+125^{\circ}C$ 28400A K2Ceramic Chip-Carrier $-40/+85^{\circ}C$ $28400B K2$ $Ceramic Chip-Carrier-40/+85^{\circ}C28400B K6Firit Seal-40/+85^{\circ}C28400B D2Ceramic0/+70^{\circ}C28400B D2Ceramic-55/+125^{\circ}C6.0 MHz28400B C1Plastic Chip-Carrier0/+70^{\circ}C28400B C1Plastic Chip-Carrier0/+70^{\circ}C28400B C6Plastic Chip-Carrier0/+70^{\circ}C28400B K1Ceramic Chip-Carrier-40/+85^{\circ}C28400B K2Ceramic Chip-Carrier-40/+85^{\circ}C28400B K2Ceramic Chip-Carrier-40/+85^{\circ}C28400B K2Ceramic Chip-Carrier-40/+85^{\circ}C28400H K1Ceramic0/+70^{\circ}C28400H F6Frit Seal0/+70^{\circ}C28400H F1Frit Seal0/+70^{\circ}C28400H C6Plastic Chip-Carrier0/+70^{\circ}C28400H C6Plastic Chip-Carrier0/+70^{\circ}C28400H C6Plastic Chip-Carrier0/+70^{\circ}C28400H C6Plastic Chip-Carrier0/+70^{\circ}C28400H C6Plastic Chip-Carrier0/+70^{\circ}C2840$		Ceramic	-40/+85°C		
28400A C1 Plastic Chip-Carrier $0/+70^{\circ}C$ 28400A C6 Plastic Chip-Carrier $-40/+85^{\circ}C$ 28400A K1 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400A K2 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400A K2 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400A K2 Ceramic Chip-Carrier $-55/+125^{\circ}C$ 73400B B1 Plastic $0/+70^{\circ}C$ 28400B F6 Frit Seal $-40/+85^{\circ}C$ 28400B D6 Ceramic $0/+70^{\circ}C$ 28400B D1 Ceramic $-40/+85^{\circ}C$ 28400B D2 Ceramic $-40/+85^{\circ}C$ 28400B C1 Plastic Chip-Carrier $0/+70^{\circ}C$ 28400B K1 Ceramic Chip-Carrier $0/+70^{\circ}C$ 28400B K1 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400B K2 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400B K2 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400B K3 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400B K4 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 28400H K1 Ceramic Chip-Carrier $-40/+85^{\circ}C$		Ceramic		4.0 MHz	
Z8400A C6Plastic Chip-Carrier $-40/+85^{\circ}C$ Z8400A K1Ceramic Chip-Carrier $0/+70^{\circ}C$ Z8400A K6Ceramic Chip-Carrier $-40/+85^{\circ}C$ Z8400A K2Ceramic Chip-Carrier $-55/+125^{\circ}C$ Z8400B S1Plastic $0/+70^{\circ}C$ Z8400B S1Plastic $0/+70^{\circ}C$ Z8400B F6Frit Seal $0/+70^{\circ}C$ Z8400B D6Ceramic $0/+70^{\circ}C$ Z8400B D6Ceramic $-40/+85^{\circ}C$ Z8400B D7Ceramic $-55/+125^{\circ}C$ Z8400B C1Plastic Chip-Carrier $0/+70^{\circ}C$ Z8400B C6Plastic Chip-Carrier $0/+70^{\circ}C$ Z8400B K1Ceramic Chip-Carrier $0/+70^{\circ}C$ Z8400B K2Ceramic Chip-Carrier $-40/+85^{\circ}C$ Z8400B K2Ceramic Chip-Carrier $-40/+85^{\circ}C$ Z8400B B1Plastic $0/+70^{\circ}C$ Z8400B B2Ceramic Chip-Carrier $-40/+85^{\circ}C$ Z8400B K2Ceramic Chip-Carrier $-40/+85^{\circ}C$ Z8400B K2Ceramic Chip-Carrier $-40/+85^{\circ}C$ Z8400H B6Plastic $-40/+85^{\circ}C$ Z8400H F6Frit Seal $-40/+85^{\circ}C$ Z8400H D6Ceramic $0/+70^{\circ}C$ Z8400H D6Ceramic Chip-Carrier $0/+70^{\circ}C$ Z8400H C6Plastic Chip-Carrier $0/$		Plastic Chip-Carrier			
Z8400A K1Ceramic Chip-Carrier $0/+70^{\circ}$ CZ8400A K6Ceramic Chip-Carrier $-40/+85^{\circ}$ CZ8400A K2Ceramic Chip-Carrier $-55'+125^{\circ}$ CZ8400B B1Plastic $0'+70^{\circ}$ CZ8400B F1Frit Seal $0'+70^{\circ}$ CZ8400B F6Frit Seal $0'+70^{\circ}$ CZ8400B D6Ceramic $0'+70^{\circ}$ CZ8400B D6Ceramic $-40'+85^{\circ}$ CZ8400B D7Ceramic $0'+70^{\circ}$ CZ8400B C1Plastic Chip-Carrier $0'+70^{\circ}$ CZ8400B C6Plastic Chip-Carrier $0'+70^{\circ}$ CZ8400B K1Ceramic Chip-Carrier $0'+70^{\circ}$ CZ8400B K2Ceramic Chip-Carrier $-40'+85^{\circ}$ CZ8400B K2Ceramic Chip-Carrier $-40'+85^{\circ}$ CZ8400B K3Ceramic Chip-Carrier $-40'+85^{\circ}$ CZ8400B K4Ceramic Chip-Carrier $-40'+85^{\circ}$ CZ8400B K5Ceramic Chip-Carrier $-40'+85^{\circ}$ CZ8400B K2Ceramic Chip-Carrier $-40'+85^{\circ}$ CZ8400H B1Plastic $0'+70^{\circ}$ CZ8400H F6Frit Seal $-40'+85^{\circ}$ CZ8400H D6Ceramic $0'+70^{\circ}$ CZ8400H D6Ceramic $0'+70^{\circ}$ CZ8400H C1Plastic Chip-Carrier $0'+70^{\circ}$ CZ8400H C5Plastic Chip-Carrier $0'+70^{\circ}$ CZ8400H C6Plastic Chip-Carrier $0'+70^{\circ}$ CZ8400H C6Plastic Chip-Carrier $0'+70^{\circ}$ CZ8400H C6Plastic Chip-Carrier $0'+70^{\circ}$ CZ8400H C6Plastic Chip-Carrier $0'+70$	Z6400A C6	•	- 40/ + 85°C		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Z8400A K1	· · · ·			
28400A K2 Ceramic Chip-Carrier $-55/+125^{\circ}C$ 284003 B1 Plastic $0/+70^{\circ}C$ 284003 B6 Plastic $-40/+85^{\circ}C$ 284003 F1 Frit Seal $0/+70^{\circ}C$ 284003 D1 Ceramic $0/+70^{\circ}C$ 284003 D1 Ceramic $0/+70^{\circ}C$ 284003 D2 Ceramic $-40/+85^{\circ}C$ 284003 D2 Ceramic $-55/+125^{\circ}C$ 284003 D2 Ceramic $-55/+125^{\circ}C$ 284003 C6 Plastic Chip-Carrier $0/+70^{\circ}C$ 284003 K1 Ceramic Chip-Carrier $0/+70^{\circ}C$ 284003 K2 Ceramic Chip-Carrier $0/+70^{\circ}C$ 284003 K2 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 284004 K1 Ceramic Chip-Carrier $-40/+85^{\circ}C$ 284004 F6 Frit Seal $0/+70^{\circ}C$ 284004 F6 Frit Seal $0/+70^{\circ}C$ 284004 C1 Plastic Chip-Carrier $0/+70^{\circ}C$ 284004 C1 Plastic Chip-Carrier $0/+70^{\circ}C$ 284004 C1 Plastic Chip-Carrier $0/+70^{\circ}C$ 284004 C5 Plastic Chip-Carrier $0/+70^{$		•			
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	Z8400A K2	-	-55/+125°C		
$ \begin{array}{cccccccccccccccccccccccccccccccccccc$	Z84003 B1	Plastic	0/+70°C		
$ \begin{array}{rcrcrcrc} 284003 & F1 & Frit Seal & 0' + 70°C \\ 284008 & F6 & Frit Seal & -40' + 85°C \\ 284008 & D1 & Ceramic & 0' + 70°C \\ 284008 & D2 & Ceramic & -40' + 85°C \\ 284008 & D2 & Ceramic & -55' + 125°C \\ 284008 & C1 & Plastic Chip-Carrier & 0' + 70°C \\ 284008 & C6 & Plastic Chip-Carrier & -40' + 85°C \\ 284008 & K1 & Ceramic Chip-Carrier & -40' + 85°C \\ 284008 & K2 & Ceramic Chip-Carrier & -40' + 85°C \\ 284008 & K2 & Ceramic Chip-Carrier & -40' + 85°C \\ 284008 & K2 & Ceramic Chip-Carrier & -55' + 125°C \\ 284008 & K2 & Ceramic Chip-Carrier & -40' + 85°C \\ 284008 & K2 & Ceramic Chip-Carrier & -40' + 85°C \\ 284008 & K2 & Ceramic Chip-Carrier & -40' + 85°C \\ 284008 & F1 & Fit Seal & 0' + 70°C \\ 284008 & F1 & Frit Seal & 0' + 70°C \\ 284008 & F6 & Frit Seal & -40' + 85°C \\ 284008 & C & Ceramic Chip-Carrier & 0' + 70°C \\ 284008 & C & Plastic Chip-Carrier & 0' + 70°C \\ 284008 & C & Plastic Chip-Carrier & 0' + 85°C \\ 284008 & C & Plastic Chip-Carrier & 0' + 70°C \\ 284008 & C & Plastic Chip-Carrier & 0' + 85°C \\ 284008 & C & Plastic Chip-Carrier & 0' + 70°C \\ 284008 & C & Plasti$	Z5-203 B6			1	
$Z8+003$ F6 Frit Seal $-40/+85^{\circ}C$ $Z24003$ D1 Ceramic $0/+70^{\circ}C$ $Z24003$ D2 Ceramic $-40/+85^{\circ}C$ $Z84003$ D2 Ceramic $-40/+85^{\circ}C$ $Z84003$ D2 Ceramic $-55/+125^{\circ}C$ $Z84003$ C1 Plastic Chip-Carrier $0/+70^{\circ}C$ $Z84003$ C6 Plastic Chip-Carrier $0/+70^{\circ}C$ $Z84003$ K1 Ceramic Chip-Carrier $0/+70^{\circ}C$ $Z84003$ K2 Ceramic Chip-Carrier $-40/+85^{\circ}C$ $Z84003$ K2 Ceramic Chip-Carrier $-55/+125^{\circ}C$ $Z84003$ K2 Ceramic Chip-Carrier $-40/+85^{\circ}C$ $Z84004$ K1 Ceramic Chip-Carrier $-40/+85^{\circ}C$ $Z84004$ F6 Frit Seal $0/+70^{\circ}C$ $Z84004$ F1 Frit Seal $-40/+85^{\circ}C$ $Z84004$ C1 Plastic Chip-Carrier $0/+70^{\circ}C$ $Z84004$ K1 Ceramic $-40/+85^{\circ}C$					
Z24003 D1 Ceramic $0' + 70^{\circ}$ C Z54003 D6 Ceramic $-40' + 88^{\circ}$ C Z24008 D2 Ceramic $-55' + 125^{\circ}$ C Z24008 C1 Plastic Chip-Carrier $0' + 70^{\circ}$ C Z24008 C6 Plastic Chip-Carrier $0' + 70^{\circ}$ C Z24008 K1 Ceramic Chip-Carrier $0' + 70^{\circ}$ C Z24008 K1 Ceramic Chip-Carrier $0' + 70^{\circ}$ C Z24008 K6 Ceramic Chip-Carrier $-40' + 88^{\circ}$ C Z34008 K2 Ceramic Chip-Carrier $-40' + 85^{\circ}$ C Z34001 B1 Plastic $0' + 70^{\circ}$ C Z34002 K2 Ceramic Chip-Carrier $-40' + 85^{\circ}$ C Z34003 K2 Ceramic Chip-Carrier $-40' + 85^{\circ}$ C Z34001 B6 Plastic $-40' + 85^{\circ}$ C Z34002 K6 Frit Seal $0' + 70^{\circ}$ C Z34004 F6 Frit Seal $0' + 70^{\circ}$ C Z34004 D1 Ceramic $0' + 70^{\circ}$ C Z34004 D6 Ceramic $-40' + 85^{\circ}$ C Z34004 D6 Plastic Chip-Carrier $0' + 70^{\circ}$ C Z34004 D6 Plastic Chip-Carrier $0' + 70^{\circ}$ C Z34004 K1					
Z54003 D6 Ceramic $-40/+85^{\circ}C$ 6.0 MHz Z84008 D2 Ceramic $-55/+125^{\circ}C$ 6.0 MHz Z84008 C1 Plastic Chip-Carrier $0/+70^{\circ}C$ 6.0 MHz Z84008 C6 Plastic Chip-Carrier $0/+70^{\circ}C$ 6.0 MHz Z84008 K1 Ceramic Chip-Carrier $0/+70^{\circ}C$ 6.0 MHz Z84008 K2 Ceramic Chip-Carrier $0/+70^{\circ}C$ 6.0 MHz Z84008 K2 Ceramic Chip-Carrier $-40/+88^{\circ}C$ 6.0 MHz Z84001 B1 Plastic $0/+70^{\circ}C$ 6.0 MHz Z84001 F6 Frit Seal $0/+70^{\circ}C$ 6.0 MHz Z84001 D1 Ceramic $0/+70^{\circ}C$ 6.0 MHz Z84001 D6 Ceramic $0/+70^{\circ}C$ 6.0 MHz Z84001 C6 Plastic Chip-Carrier $0/+70^{\circ}C$ 6.0 MHz Z84001 K1 Ceramic Chip-Carrier $0/+70^{\circ}C$ 6.0 MHz					
Z84003 D2 Ceramic -55/+125°C 6.0 MHz Z84008 C1 Plastic Chip-Carrier 0/+70°C 6.0 MHz Z84008 C6 Plastic Chip-Carrier 0/+70°C 6.0 MHz Z84008 K1 Ceramic Chip-Carrier -40/+85°C 6.0 MHz Z84008 K1 Ceramic Chip-Carrier 0/+70°C 6.0 MHz Z84008 K2 Ceramic Chip-Carrier -40/+85°C 6.0 MHz Z84008 K2 Ceramic Chip-Carrier -40/+85°C 7.0 C Z84008 K2 Ceramic Chip-Carrier -55/+125°C 7.0 C Z8400H B1 Plastic 0/+70°C 7.0 C Z8400H F6 Frit Seal 0/+70°C 7.0 C Z8400H D6 Ceramic 0/+70°C 8.0 MHz Z8400H D6 Ceramic Chip-Carrier 0/+70°C 8.0 MHz Z8400H C6 Plastic Chip-Carrier 0/+70°C 8.0 MHz Z8400H C6 Plastic Chip-Carrier 0/+70°C 7.0 C Z8400H K1 Ceramic Chip-Carrier 0/+70°C 7.0 C Z8400H K1 Ceramic Chip-Carrier 0/+70°C 8.0 MHz <td>Z5400B D6</td> <td></td> <td></td> <td></td> <td></td>	Z5400B D6				
28400B C1 Plastic Chip-Carrier 0/ + 70°C 28400B C6 Plastic Chip-Carrier - 40/ + 85°C 28400B K1 Ceramic Chip-Carrier 0/ + 70°C 28400B K6 Ceramic Chip-Carrier - 40/ + 85°C 28400B K6 Ceramic Chip-Carrier - 40/ + 85°C 28400B K2 Ceramic Chip-Carrier - 55/ + 125°C 28400H B1 Plastic 0/ + 70°C 28400H S1 Flastic - 40/ + 85°C 28400H F6 Frit Seal 0/ + 70°C 28400H D6 Ceramic 0/ + 70°C 28400H D6 Ceramic 0/ + 70°C 28400H C1 Plastic Chip-Carrier - 40/ + 85°C 28400H C5 Plastic Chip-Carrier 0/ + 70°C 28400H C6 Plastic Chip-Carrier - 40/ + 85°C 28400H K1 Ceramic Chip-Carrier - 40/ + 85°C 28400H K1 Ceramic Chip-Carrier - 40/ + 85°C				6.0 MHz	
Z84008 C6 Plastic Chip-Carrier - 40/ + 85°C Z84008 K1 Ceramic Chip-Carrier 0/ + 70°C Z84008 K6 Ceramic Chip-Carrier - 40/ + 85°C Z84008 K2 Ceramic Chip-Carrier - 40/ + 85°C Z84008 K2 Ceramic Chip-Carrier - 55/ + 125°C Z8400H B1 Plastic 0/ + 70°C Z8400H F1 Frit Seal 0/ + 70°C Z8400H F6 Frit Seal 0/ + 85°C Z8400H D6 Ceramic 0/ + 70°C Z8400H C1 Plastic Chip-Carrier - 40/ + 85°C Z8400H C6 Plastic Chip-Carrier 0/ + 70°C Z8400H K1 Ceramic Chip-Carrier - 40/ + 85°C Z8400H K1 Ceramic Chip-Carrier - 40/ + 85°C					
Z8400B K1 Ceramic Chip-Carrier 0/ + 70°C Z8400B K6 Ceramic Chip-Carrier - 40/ + 85°C Z8400B K2 Ceramic Chip-Carrier - 55/ + 125°C Z8400H B1 Plastic 0/ + 70°C Z8400H B1 Plastic 0/ + 70°C Z8400H B6 Plastic - 40/ + 85°C Z8400H F6 Frit Seal 0/ + 70°C Z8400H F6 Frit Seal - 40/ + 85°C Z8400H D1 Ceramic 0/ + 70°C Z8400H D6 Ceramic 0/ + 70°C Z8400H C1 Plastic Chip-Carrier - 40/ + 85°C Z8400H C6 Plastic Chip-Carrier - 40/ + 85°C Z8400H K1 Ceramic 0/ + 70°C Z8400H K1 Ceramic Chip-Carrier - 40/ + 85°C					
Z84003 K6 Ceramic Chip-Carrier -40/+85°C Z84003 K2 Ceramic Chip-Carrier -55/+125°C Z84001 B1 Plastic 0/+70°C Z84001 B6 Plastic -40/+85°C; Z84001 B6 Plastic -40/+85°C; Z84001 F6 Frit Seal 0/+70°C Z84001 D1 Ceramic 0/+70°C Z84001 D6 Ceramic 0/+70°C Z84001 C1 Plastic Chip-Carrier 0/+85°C Z84001 C6 Plastic Chip-Carrier 0/+70°C Z84001 C6 Plastic Chip-Carrier -40/+85°C Z84001 K1 Ceramic Chip-Carrier -40/+85°C Z84001 K1 Ceramic Chip-Carrier -40/+85°C	Z8400B K1	•			
Z34003 K2 Ceramic Chip-Carrier -55/+125°C Z3400H B1 Plastic 0/+70°C Z3400H B6 Plastic -40/+85°C; Z3400H F6 Frit Seal 0/+70°C Z3400H F6 Frit Seal 0/+70°C Z3400H D1 Ceramic 0/+70°C Z3400H D6 Ceramic 0/+70°C Z3400H C1 Plastic Chip-Carrier 0/+70°C Z3400H C6 Plastic Chip-Carrier 0/+70°C Z3400H K1 Ceramic Chip-Carrier -40/+85°C Z3400H K1 Ceramic Chip-Carrier -40/+85°C		•			
Z3+00H B6 Plastic -40/+85°C; Z3+00H F1 Frit Seal 0/+70°C Z3400H F6 Frit Seal -40/+85°C Z3400H D1 Ceramic 0/+70°C Z3400H D6 Ceramic -40/+85°C 8.0 MHz Z3400H C1 Plastic Chip-Carrier 0/+70°C 8.0 MHz Z3400H C6 Plastic Chip-Carrier -40/+85°C 8.0 MHz Z3400H K1 Ceramic Chip-Carrier -40/+85°C 8.0 MHz	Z8400B K2	•			
Z3+00H B6 Plastic -40/+85°C; Z3+00H F1 Frit Seal 0/+70°C Z3400H F6 Frit Seal -40/+85°C Z3400H D1 Ceramic 0/+70°C Z3400H D6 Ceramic -40/+85°C 8.0 MHz Z3400H C1 Plastic Chip-Carrier 0/+70°C 8.0 MHz Z3400H C6 Plastic Chip-Carrier -40/+85°C 8.0 MHz Z3400H K1 Ceramic Chip-Carrier -40/+85°C 8.0 MHz		Plastic	,		
Z8+20H F1 Frit Seal 0/ + 70°C Z3400H F6 Frit Seal - 40/ + 85°C Z8+20H D1 Ceramic 0/ + 70°C Z8400H D6 Ceramic 0/ + 70°C Z8400H C6 Plastic Chip-Carrier 0/ + 70°C Z8400H C6 Plastic Chip-Carrier - 40/ + 85°C Z8400H C6 Ceramic - 40/ + 85°C Z8400H K1 Ceramic - 40/ + 85°C				1	
Z3400H F6 Frit Seal - 40/ + 85°C 8.0 MHz Z3400H D1 Ceramic 0/ + 70°C 8.0 MHz Z3400H D6 Ceramic - 40/ + 85°C 8.0 MHz Z3400H C6 Plastic Chip-Carrier 0/ + 70°C 8.0 MHz Z3400H C6 Plastic Chip-Carrier - 40/ + 85°C 2400H K1 Ceramic Ceramic - 40/ + 85°C 2400H K1 Ceramic Chip-Carrier - 40/ + 85°C 2400H K1 Ceramic Chip-Carrier - 40/ + 85°C 2400H K1 Ceramic Chip-Carrier - 40/ + 85°C 2400H K1 - 40/ + 85°C - 40/ + 85°C <td></td> <td></td> <td>•</td> <td>1</td> <td></td>			•	1	
Z3400H D1 Ceramic 0/ + 70°C 8.0 MHz Z3400H D6 Ceramic - 40/ + 85°C 8.0 MHz Z8400H C1 Plastic Chip-Carrier 0/ + 70°C 8.0 MHz Z8400H C6 Plastic Chip-Carrier - 40/ + 85°C 8.0 MHz Z8400H K1 Ceramic Chip-Carrier - 40/ + 85°C 8.0 MHz	Z8400H F6			1	
23400H D6 Ceramic - 40/ + 85°C 8.0 MHz 28400H C1 Plastic Chip-Carrier 0/ + 70°C 700°C 28400H C6 Plastic Chip-Carrier - 40/ + 85°C 700°C 28400H K1 Ceramic Chip-Carrier - 40/ + 85°C 70°C	28+00H D1				
28400H C1 Plastic Chip-Carrier 0/ + 70°C 28400H C6 Plastic Chip-Carrier - 40/ + 85°C 28400H K1 Ceramic Chip-Carrier 0/ + 70°C				8.0 MHz	
Z8400H C6 Plastic Chip-Carrier – 40/+85°C Z8400H K1 Ceramic Chip-Carrier 0/+70°C		-			
23400H KI Ceramic Chip-Carrier $0/+70^{\circ}$ C	28400H C6	•)	
28400H K6 Ceramic Chip-Carrier -40/+,85°C	28400H KI	•		1	
Ceranic Cilp-Carrier	28400H K6	•		1	
		Ceranuc Ontp-Carrier			